

PCN# 20180322003
Transfer of select LDMOS devices from GFAB to FFAB Wafer Fab site
Change Notification / Sample Request

Date: March 23, 2018
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20180322003
Attachment: 1



Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM2671M-5.0/NOPB	null
LM2673S-3.3/NOPB	null
LM2674M-ADJ/NOPB	null
LM2675M-3.3/NOPB	null
LM2675M-ADJ/NOPB	null
LM2676S-ADJ/NOPB	null
LM2650M-ADJ/NOPB	null
LM2670S-3.3/NOPB	null
LM2670S-5.0/NOPB	null
LM2670S-ADJ/NOPB	null
LM2670SX-5.0/NOPB	null
LM2670SX-ADJ/NOPB	null
LM2670T-ADJ/NOPB	null
LM2671M-12/NOPB	null
LM2671M-3.3/NOPB	null
LM2671M-ADJ/NOPB	null
LM2671MX-ADJ/NOPB	null
LM2672M-12/NOPB	null
LM2672M-3.3/NOPB	null
LM2672M-5.0/NOPB	null
LM2672M-ADJ/NOPB	null
LM2672MX-3.3/NOPB	null
LM2672MX-5.0/NOPB	null
LM2672MX-ADJ/NOPB	null
LM2672N-5.0/NOPB	null
LM2672N-ADJ/NOPB	null
LM2673S-12/NOPB	null
LM2673S-5.0/NOPB	null
LM2673S-ADJ/NOPB	null
LM2673SX-5.0/NOPB	null
LM2673SX-ADJ/NOPB	null
LM2673T-5.0/NOPB	null
LM2673T-ADJ/NOPB	null
LM2674M-12/NOPB	null
LM2674M-3.3/NOPB	null
LM2674M-5.0/NOPB	null
LM2674MX-12/NOPB	null
LM2674MX-3.3/NOPB	null
LM2674MX-5.0/NOPB	null
LM2674MX-ADJ/NOPB	null
LM2674N-5.0/NOPB	null
LM2674N-ADJ/NOPB	null
LM2675M-12/NOPB	null
LM2675M-5.0/NOPB	null
LM2675MX-12/NOPB	null
LM2675MX-3.3/NOPB	null
LM2675MX-5.0/NOPB	null
LM2675MX-ADJ/NOPB	null
LM2675N-5.0/NOPB	null
LM2676S-12/NOPB	null
LM2676S-3.3/NOPB	null
LM2676S-5.0/NOPB	null
LM2676SD-5.0/NOPB	null
LM2676SX-12/NOPB	null
LM2676SX-3.3/NOPB	null
LM2676SX-5.0/NOPB	null
LM2676SX-ADJ/NOPB	null
LM2676T-12/NOPB	null
LM2676T-5.0/NOPB	null
LM2676T-ADJ/NOPB	null
LM2677S-3.3/NOPB	null
LM2677S-5.0/NOPB	null

LM2677S-ADJ/NOPB	null
LM2677T-ADJ/NOPB	null
LM2678S-12/NOPB	null
LM2678S-3.3/NOPB	null
LM2678S-5.0/NOPB	null
LM2678S-ADJ/NOPB	null
LM2678SX-5.0/NOPB	null
LM2678SX-ADJ/NOPB	null
LM2678T-12/NOPB	null
LM2678T-5.0/NOPB	null
LM2678T-ADJ/NOPB	null
LM2679S-5.0/NOPB	null
LM2679S-ADJ/NOPB	null
LM2679SX-ADJ/NOPB	null
LM2679T-5.0/NOPB	null
LM2671MX-5.0/NOPB	null
LM2677S-12/NOPB	null
LM2679T-ADJ/NOPB	null
LM2675N-ADJ/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180322003	PCN Date:	Mar 23, 2018
Title:	Transfer of select LMDMOS devices from GFAB to FFAB Wafer Fab site		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jun 23, 2018	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
PCN Details			
Description of Change:			
This change notification is to announce the transfer of select LMDMOS devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.			
Current Fab Site		New Fab Site	
Current Fab Site	Process	Wafer Diameter	New Fab Site
GFAB6	LMDMOS	150 mm	FFAB
GFAB8	LMDMOS	200 mm	FFAB
			Process
			LMDMOS
			Wafer Diameter
			200 mm
			200 mm
Qual details are provided in the Qual Data Section.			
Reason for Change:			
Greenock, Scotland (GFAB) Wafer Fab site closure			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
Current:			
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock
New Fab Site:			
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising
Sample product shipping label (not actual product label)			
 MADE IN: Malaysia 2DC: 2d: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033517 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
Product Affected:			
LM2640MTCX-ADJ/NOPB	LM2672N-12/NOPB	LM2675MX-3.3/NAK2	LM2677T-ADJ
LM2650M-ADJ/NOPB	LM2672N-3.3/NOPB	LM2675MX-3.3/NOPB	LM2677T-ADJ/NOPB
LM2650MX-ADJ/NOPB	LM2672N-5.0/NOPB	LM2675MX-5.0/NOPB	LM2678S-12

LM2670S-12/NOPB	LM2672N-ADJ/NOPB	LM2675MX-ADJ/J7002911	LM2678S-12/NOPB
LM2670S-3.3/NOPB	LM2673S-12	LM2675MX-ADJ/NOPB	LM2678S-3.3
LM2670S-5.0	LM2673S-12/NOPB	LM2675N-12/NOPB	LM2678S-3.3/NOPB
LM2670S-5.0/NOPB	LM2673S-3.3	LM2675N-3.3/NOPB	LM2678S-5.0
LM2670S-ADJ	LM2673S-3.3/NOPB	LM2675N-5.0/NOPB	LM2678S-5.0/NOPB
LM2670S-ADJ/NOPB	LM2673S-5.0	LM2675N-ADJ/NOPB	LM2678S-ADJ
LM2670SD-12/NOPB	LM2673S-5.0/NOPB	LM2676S-12	LM2678S-ADJ/NOPB
LM2670SD-3.3/NOPB	LM2673S-ADJ	LM2676S-12/NOPB	LM2678SD-12
LM2670SD-5.0/NOPB	LM2673S-ADJ/NOPB	LM2676S-3.3	LM2678SD-12/NOPB
LM2670SD-ADJ/NOPB	LM2673SD-12/NOPB	LM2676S-3.3/NOPB	LM2678SD-3.3/NOPB
LM2670SDX-3.3/NOPB	LM2673SD-3.3/NOPB	LM2676S-5.0	LM2678SD-5.0/NOPB
LM2670SDX-5.0/NOPB	LM2673SD-5.0/NOPB	LM2676S-5.0/NOPB	LM2678SD-ADJ
LM2670SDX-ADJ/NOPB	LM2673SD-ADJ/NOPB	LM2676S-ADJ	LM2678SD-ADJ/NOPB
LM2670SX-12/NOPB	LM2673SDX-3.3/NOPB	LM2676S-ADJ/NOPB	LM2678SDX-3.3/NOPB
LM2670SX-3.3/NOPB	LM2673SDX-5.0/NOPB	LM2676SD-12/NOPB	LM2678SDX-5.0/NOPB
LM2670SX-5.0/NOPB	LM2673SDX-ADJ/NOPB	LM2676SD-3.3	LM2678SDX-ADJ/NOPB
LM2670SX-ADJ/NOPB	LM2673SX-12/NOPB	LM2676SD-3.3/NOPB	LM2678SX-12/NOPB
LM2670T-12/NOPB	LM2673SX-3.3/NOPB	LM2676SD-5.0/NOPB	LM2678SX-3.3/NOPB
LM2670T-3.3/NOPB	LM2673SX-5.0/NOPB	LM2676SD-ADJ/NOPB	LM2678SX-5.0/NOPB
LM2670T-5.0/NOPB	LM2673SX-ADJ	LM2676SDX-3.3/NOPB	LM2678SX-ADJ
LM2670T-ADJ/NOPB	LM2673SX-ADJ/NOPB	LM2676SDX-5.0/NOPB	LM2678SX-ADJ/J7001756
LM2671LD-ADJ	LM2673T-12/NOPB	LM2676SDX-ADJ	LM2678SX-ADJ/NOPB
LM2671LD-ADJ/NOPB	LM2673T-5.0/NOPB	LM2676SDX-ADJ/NOPB	LM2678T-12/NOPB
LM2671M-12/NOPB	LM2673T-ADJ	LM2676SX-12/NOPB	LM2678T-3.3/NOPB
LM2671M-3.3/NOPB	LM2673T-ADJ/NOPB	LM2676SX-3.3/NOPB	LM2678T-5.0
LM2671M-5.0	LM2674LD-ADJ/NOPB	LM2676SX-5.0	LM2678T-5.0/NOPB
LM2671M-5.0/NOPB	LM2674LDX-5.0/NOPB	LM2676SX-5.0/NOPB	LM2678T-ADJ
LM2671M-ADJ	LM2674M-12	LM2676SX-ADJ	LM2678T-ADJ/NOPB
LM2671M-ADJ/NOPB	LM2674M-12/NOPB	LM2676SX-ADJ/J7001886	LM2678T-ADJ/S7002204
LM2671MX-12/NOPB	LM2674M-3.3/NOPB	LM2676SX-ADJ/NOPB	LM2679S-12/NOPB
LM2671MX-3.3/NOPB	LM2674M-5.0	LM2676T-12/NOPB	LM2679S-3.3
LM2671MX-5.0/NOPB	LM2674M-5.0/NOPB	LM2676T-3.3/NOPB	LM2679S-3.3/NOPB
LM2671MX-ADJ/NOPB	LM2674M-ADJ/NOPB	LM2676T-5.0/NOPB	LM2679S-5.0
LM2671N-12/NOPB	LM2674MX-12/NOPB	LM2676T-ADJ	LM2679S-5.0/NOPB
LM2671N-3.3/NOPB	LM2674MX-3.3/NOPB	LM2676T-ADJ/NOPB	LM2679S-ADJ
LM2671N-5.0/NOPB	LM2674MX-5.0/NOPB	LM2677S-12/NOPB	LM2679S-ADJ/NOPB
LM2671N-ADJ/NOPB	LM2674MX-ADJ/NOPB	LM2677S-3.3/NOPB	LM2679SD-3.3/NOPB
LM2672LD-ADJ/NOPB	LM2674N-3.3/NOPB	LM2677S-5.0	LM2679SD-5.0/NOPB
LM2672M-12/NOPB	LM2674N-5.0/NOPB	LM2677S-5.0/NOPB	LM2679SD-ADJ/NOPB
LM2672M-3.3	LM2674N-ADJ/NOPB	LM2677S-ADJ	LM2679SDX-3.3/NOPB
LM2672M-3.3/NOPB	LM2675LD-5.0	LM2677S-ADJ/NOPB	LM2679SDX-ADJ/NOPB
LM2672M-5.0	LM2675LD-5.0/NOPB	LM2677SD-3.3/NOPB	LM2679SX-12/NOPB
LM2672M-5.0/NOPB	LM2675LD-ADJ/NOPB	LM2677SD-5.0/NOPB	LM2679SX-3.3/NOPB
LM2672M-ADJ	LM2675M-12	LM2677SD-ADJ	LM2679SX-5.0
LM2672M-ADJ/NOPB	LM2675M-12/NOPB	LM2677SD-ADJ/NOPB	LM2679SX-5.0/NOPB
LM2672MX-12/NOPB	LM2675M-3.3/NOPB	LM2677SX-12/NOPB	LM2679SX-ADJ

LM2672MX-3.3/NOPB	LM2675M-5.0	LM2677SX-3.3/NOPB	LM2679SX-ADJ/NOPB
LM2672MX-5.0	LM2675M-5.0/NOPB	LM2677SX-5.0/NOPB	LM2679T-12/NOPB
LM2672MX-5.0/NOPB	LM2675M-ADJ	LM2677SX-ADJ/NOPB	LM2679T-3.3/NOPB
LM2672MX-ADJ	LM2675M-ADJ/NOPB	LM2677T-12/NOPB	LM2679T-5.0
LM2672MX-ADJ/E7000820	LM2675MX-12/NOPB	LM2677T-3.3/NOPB	LM2679T-5.0/NOPB
LM2672MX-ADJ/NOPB	LM2675MX-3.3/E7002948	LM2677T-5.0/NOPB	LM2679T-ADJ/NOPB

Qualification Report

FFAB Process Qualification LMDMOS - RLM2675B50B - LM2675M-5.0/NOPB Approve Date 01-Mar-2018

Product Attributes

Attributes	Qual Device: LM2675M-5.0/NOPB
Assembly Site	TIEM
Package Family	SOIC
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	FFAB
Wafer Process	LMDMOS

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL1-260CG: LM2675M-5.0/NOPB

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM2675M-5.0/NOPB
AC	Autoclave 121C	96 Hours	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HBM	ESD - HBM	1500 V	3/9/0
CDM	ESD - CDM	1500 V	3/9/0
HTOL	Life Test, 125C	1000 HOURS	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 HOURS	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
WLR	Wafer level Reliability	(Per Site Specification)	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com